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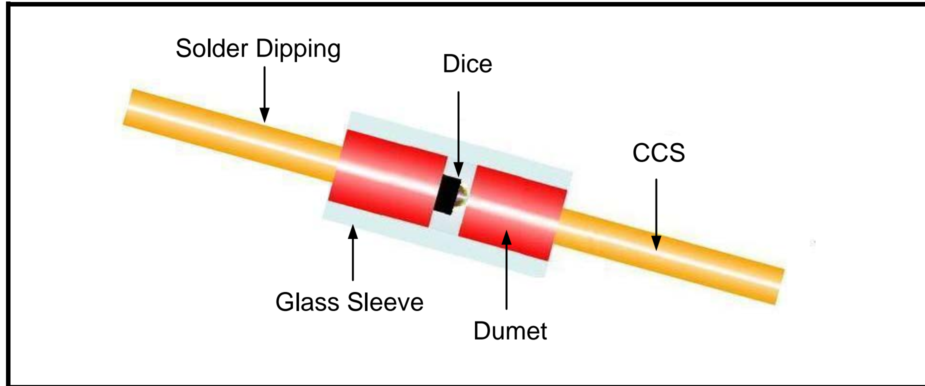
Chemical Composition of Diode (DO-34)



Weight: 92 mg / pc

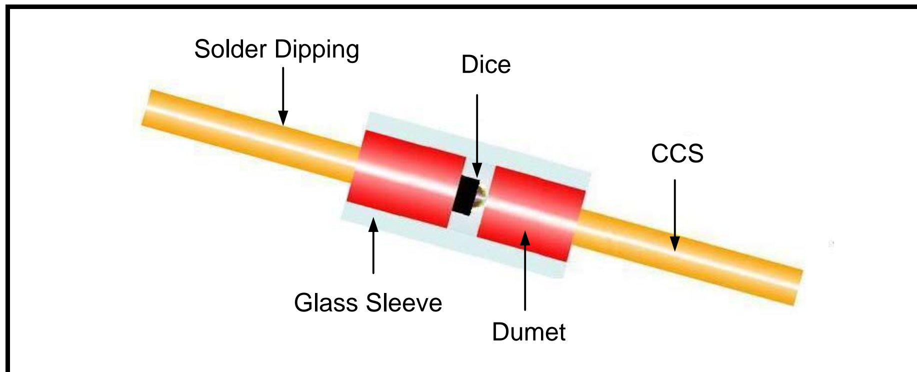
15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Solder Dipping (0.4 mg)		Sn	7440-31-5	99.95 min.	99.97	0.39988
		Others	——	0.05 max.	0.03	0.00012
Glass Sleeve (26.08 mg)		PbO	1317-36-8	50 min.	60.5	15.7784
		SiO_2	7631-86-9	10-50	33	8.6064
		K_2O	12136-45-7	1-10	4	1.0432
		B_2O_3	1303-86-2	1-10	2.5	0.652
Lead Wire-Dumet (8.1 mg)	Core material (6.156 mg)	Ni	7440-02-0	41-43	42.15	2.594754
		Fe	7439-89-6	balance	57.85	3.561246
	Cladding copper (1.944 mg)	Cu	7440-50-8	100	100	1.944
Lead Wire-CCS (57.22 mg)		Fe	7439-89-6	82	82	46.9204
		Cu	7440-50-8	18	18	10.2996
Dice (0.05 mg)		Si	7440-21-3	70.9	70.9	0.03545
		Al	7429-90-5	0.1	0.1	0.00005
		Ag	7440-22-4	28.6	28.6	0.0143
		Ni	7440-02-0	0.4	0.4	0.00020
Ink (0.15 mg)		C	7440-44-0	100	100	0.15

Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

ISO/TS 16949 : 2009 Certificate No. 05103
ISO14001 : 2004 Certificate No. 7116
ISO 9001 : 2008 Certificate No. 0506098
BS-OHSAS 18001 : 2007 Certificate No. 7116
IECQ QC 080000

Chemical Composition of Diode (DO-35)



Weight: 125 mg / pc

15-Nov-07

<table>
<tr><th colspan="2">Make up of material</th><th>Chemical Composition</th><th>CAS No.</th><th>Content Spec. (%)</th><th>Content (%)</th><th>Substance Weight (mg)</th></tr>
<tr><td colspan="2" rowspan="2">Solder Dipping (1 mg)</td><td>Sn</td><td>7440-31-5</td><td>99.95 min.</td><td>99.97</td><td>0.9997</td></tr>
<tr><td>Others</td><td>——</td><td>0.05 max.</td><td>0.03</td><td>0.0003</td></tr>
<tr><td colspan="2" rowspan="4">Glass Sleeve (33 mg)</td><td>PbO</td><td>1317-36-8</td><td>50 min.</td><td>60.5</td><td>19.965</td></tr>
<tr><td>SiO_2</td><td>7631-86-9</td><td>10-50</td><td>33</td><td>10.89</td></tr>
<tr><td>K_2O</td><td>12136-45-7</td><td>1-10</td><td>4</td><td>1.32</td></tr>
<tr><td>B_2O_3</td><td>1303-86-2</td><td>1-10</td><td>2.5</td><td>0.825</td></tr>
<tr><td rowspan="3">Lead Wire-Dumet (11 mg)</td><td rowspan="2">Core material (8.36 mg)</td><td>Ni</td><td>7440-02-0</td><td>41-43</td><td>42.15</td><td>3.52374</td></tr>
<tr><td>Fe</td><td>7439-89-6</td><td>balance</td><td>57.85</td><td>4.83626</td></tr>
<tr><td>Cladding copper (2.64 mg)</td><td>Cu</td><td>7440-50-8</td><td>100</td><td>100</td><td>2.64</td></tr>
<tr><td colspan="2" rowspan="2">Lead Wire-CCS (79.72 mg)</td><td>Fe</td><td>7439-89-6</td><td>82</td><td>82</td><td>65.3704</td></tr>
<tr><td>Cu</td><td>7440-50-8</td><td>18</td><td>18</td><td>14.3496</td></tr>
<tr><td colspan="2" rowspan="4">Dice (0.05 mg)</td><td>Si</td><td>7440-21-3</td><td>70.9</td><td>70.9</td><td>0.03545</td></tr>
<tr><td>Al</td><td>7429-90-5</td><td>0.1</td><td>0.1</td><td>0.00005</td></tr>
<tr><td>Ag</td><td>7440-22-4</td><td>28.6</td><td>28.6</td><td>0.0143</td></tr>
<tr><td>Ni</td><td>7440-02-0</td><td>0.4</td><td>0.4</td><td>0.0002</td></tr>
<tr><td colspan="2">Ink (0.23 mg)</td><td>C</td><td>7440-44-0</td><td>100</td><td>100</td><td>0.23</td></tr>
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Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

ISO/TS 16949 : 2009 Certificate No. 05103
ISO14001 : 2004 Certificate No. 7116
ISO 9001 : 2008 Certificate No. 0506098
BS-OHSAS 18001 : 2007 Certificate No. 7116
IECQ QC 080000 Certificate No. PRC-HSPM-1483-1

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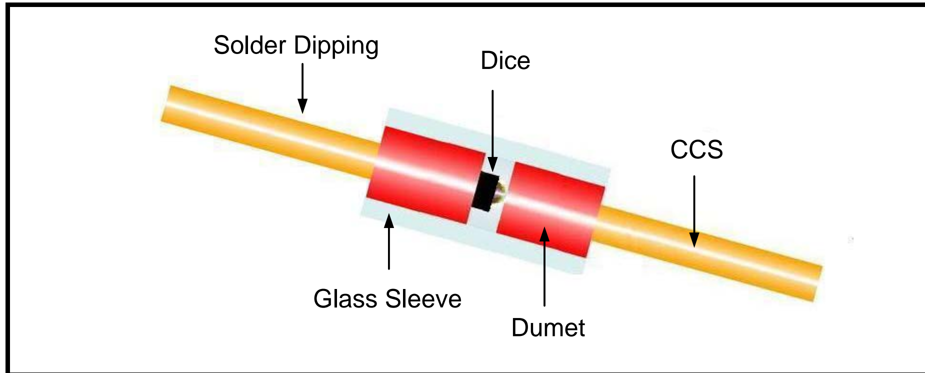
Chemical Composition of Diode (DO-41 Glass)



Weight: 253 mg / pc

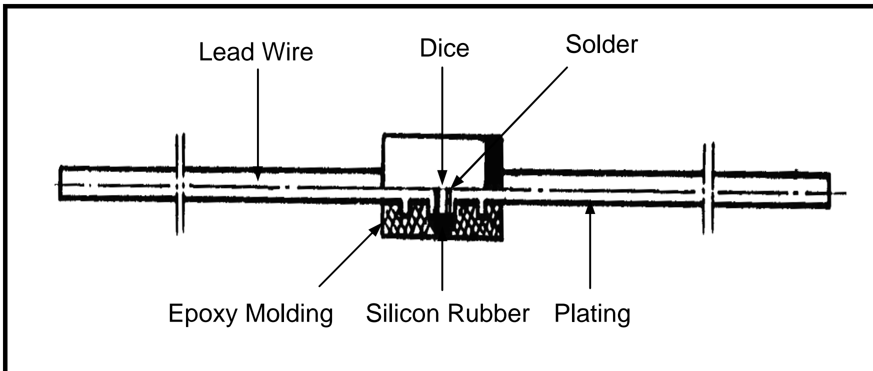
15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Solder Dipping (5 mg)		Sn	7440-31-5	99.95 min.	99.97	4.9985
		Others	——	0.05 max.	0.03	0.0015
Glass Sleeve (49.835 mg)		PbO	1317-36-8	50 min.	60.5	30.150175
		SiO_2	7631-86-9	10-50	33	16.44555
		K_2O	12136-45-7	1-10	4	1.9934
		B_2O_3	1303-86-2	1-10	2.5	1.245875
Lead Wire-Dumet (47.234 mg)	Core material (35.89784 mg)	Ni	7440-02-0	41-43	42.15	15.13093956
		Fe	7439-89-6	balance	57.85	20.76690044
	Cladding copper (11.33616 mg)	Cu	7440-50-8	100	100	11.33616
Lead Wire-CCS (150.336 mg)		Fe	7439-89-6	82	82	123.27552
		Cu	7440-50-8	18	18	27.06048
Dice (0.165 mg)		Si	7440-21-3	70.9	70.9	0.116985
		Al	7429-90-5	0.1	0.1	0.000165
		Ag	7440-22-4	28.6	28.6	0.04719
		Ni	7440-02-0	0.4	0.4	0.00066
Ink (0.43 mg)		C	7440-44-0	100	100	0.43

Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

ISO/TS 16949 : 2009 Certificate No. 05103
ISO14001 : 2004 Certificate No. 7116
ISO 9001 : 2008 Certificate No. 0506098
BS-OHSAS 18001 : 2007 Certificate No. 7116
IECQ QC 080000

Chemical Composition of Diode (DO-41 Plastic)



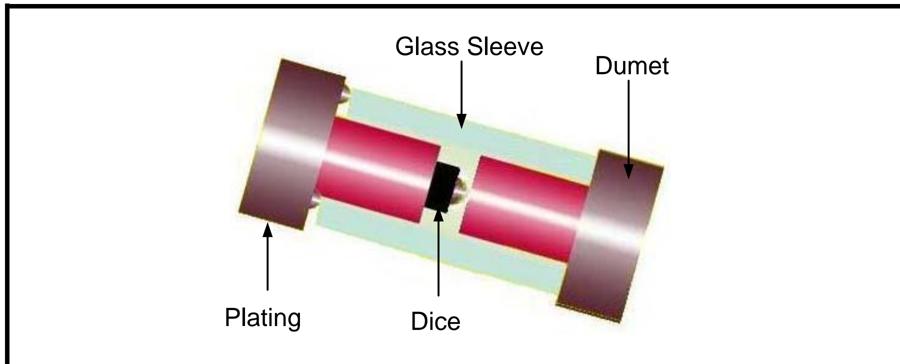
Weight: 328 mg / pc

15-Nov-07

Make up of material	Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (5.757 mg)	Sn	7440-31-5	99.95 min.	99.97	5.7552729
	Others	——	0.05 max.	0.03	0.0017271
Solder (0.5 mg)	Pb	7439-92-1	92.5	92.5	0.4625
	Ag	7440-22-4	5	5	0.025
	Cu	7440-50-8	2.5	2.5	0.0125
Epoxy Molding (98.4 mg)	Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	76.9488
	Cristobalite	14464-46-1	0 - 1	0.5	0.492
	Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	11	10.824
	Phenolic Resin Water-Soluble	9003-35-4	2 - 15	10	9.84
	Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.2952
Lead Wire (221.59 mg)	Cu	7440-50-8	100	100	221.59
Dice (0.693 mg)	Si	7440-21-3	90.8	90.8	0.629244
	P	7723-14-0	2.5	2.5	0.017325
	Ni	7440-02-0	5	5	0.03465
	Be	7440-41-7	1.7	1.7	0.011781
Silicon Rubber (1 mg)	Si	7440-21-3	100	100	1
Ink (0.06 mg)	C	7440-44-0	100	100	0.06

Note: Lead (Pb) in high melting temperature type solders is exempted from RoHS directive (EU Directive 2002/95/EC).

Chemical Composition of Diode (LS-31)



Weight: 12.3 mg / pc

15-Nov-07

<table>
<tr><th colspan="2">Make up of material</th><th>Chemical Composition</th><th>CAS No.</th><th>Content Spec. (%)</th><th>Content (%)</th><th>Substance Weight (mg)</th></tr>
<tr><td colspan="2" rowspan="2">Plating (0.25 mg)</td><td>Sn</td><td>7440-31-5</td><td>99.95 min.</td><td>99.97</td><td>0.249925</td></tr>
<tr><td>Others</td><td>——</td><td>0.05 max.</td><td>0.03</td><td>0.000075</td></tr>
<tr><td colspan="2" rowspan="4">Glass Sleeve (4.4 mg)</td><td>PbO</td><td>1317-36-8</td><td>50 min.</td><td>60.5</td><td>2.662</td></tr>
<tr><td>SiO_2</td><td>7631-86-9</td><td>10-50</td><td>33</td><td>1.452</td></tr>
<tr><td>K_2O</td><td>12136-45-7</td><td>1-10</td><td>4</td><td>0.176</td></tr>
<tr><td>B_2O_3</td><td>1303-86-2</td><td>1-10</td><td>2.5</td><td>0.11</td></tr>
<tr><td rowspan="3">Lead Wire-Dumet (7.5 mg)</td><td rowspan="2">Core material (5.7 mg)</td><td>Ni</td><td>7440-02-0</td><td>41-43</td><td>42.15</td><td>2.40255</td></tr>
<tr><td>Fe</td><td>7439-89-6</td><td>balance</td><td>57.85</td><td>3.29745</td></tr>
<tr><td>Cladding copper (1.8 mg)</td><td>Cu</td><td>7440-50-8</td><td>100</td><td>100</td><td>1.8</td></tr>
<tr><td colspan="2" rowspan="4">Dice (0.05 mg)</td><td>Si</td><td>7440-21-3</td><td>70.9</td><td>70.9</td><td>0.03545</td></tr>
<tr><td>Al</td><td>7429-90-5</td><td>0.1</td><td>0.1</td><td>0.00005</td></tr>
<tr><td>Ag</td><td>7440-22-4</td><td>28.6</td><td>28.6</td><td>0.0143</td></tr>
<tr><td>Ni</td><td>7440-02-0</td><td>0.4</td><td>0.4</td><td>0.0002</td></tr>
<tr><td colspan="2">Ink (0.1 mg)</td><td>C</td><td>7440-44-0</td><td>100</td><td>100</td><td>0.1</td></tr>
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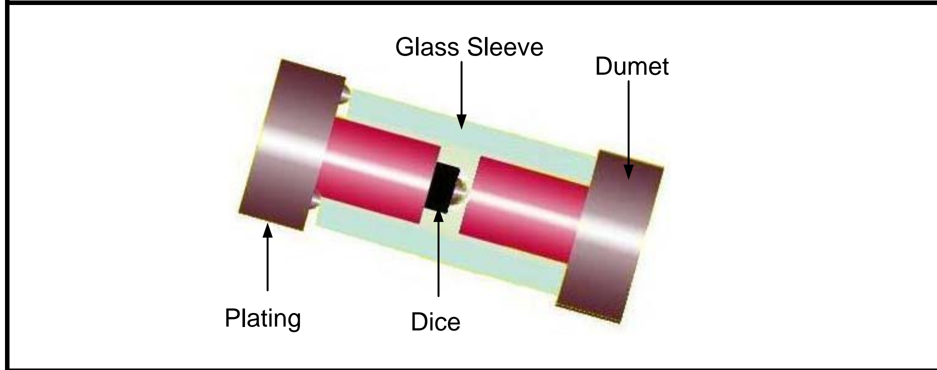
Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive(EU Directive 2002/95/EC)

Chemical Composition of Diode (LS-34)



Weight: 30.8 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.3 mg)		Sn	7440-31-5	99.95 min.	99.97	0.29991
		Others	——	0.05 max.	0.03	0.00009
Glass Sleeve (11.66 mg)		PbO	1317-36-8	50 min.	60.5	7.0543
		SiO_2	7631-86-9	10-50	33	3.8478
		K_2O	12136-45-7	1-10	4	0.4664
		B_2O_3	1303-86-2	1-10	2.5	0.2915
Lead Wire-Dumet (18.6 mg)	Core material (14.136 mg)	Ni	7440-02-0	41-43	42.15	5.958324
		Fe	7439-89-6	balance	57.85	8.177676
	Cladding copper (4.464 mg)	Cu	7440-50-8	100	100	4.464
Dice (0.05 mg)		Si	7440-21-3	70.9	70.9	0.03545
		Al	7429-90-5	0.1	0.1	0.00005
		Ag	7440-22-4	28.6	28.6	0.0143
		Ni	7440-02-0	0.4	0.4	0.0002
Ink (0.19 mg)		C	7440-44-0	100	100	0.19

Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

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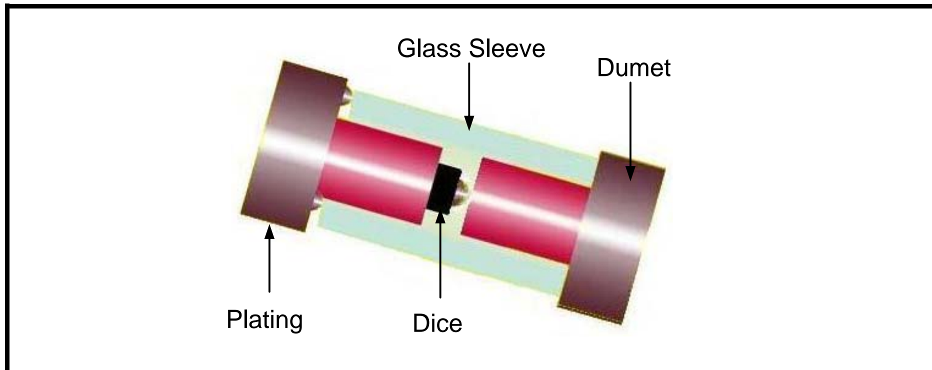
IECQ QC 080000

Chemical Composition of Diode (LL-34)



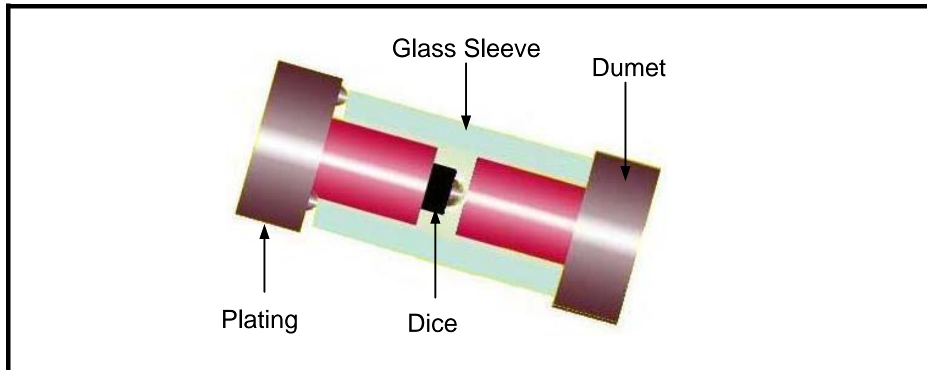
Weight: 30.6 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.3 mg)		Sn	7440-31-5	99.95 min.	99.97	0.29991
		Others	——	0.05 max.	0.03	0.00009
Glass Sleeve (11.46 mg)		PbO	1317-36-8	50 min.	60.5	6.9333
		SiO_2	7631-86-9	10-50	33	3.7818
		K_2O	12136-45-7	1-10	4	0.4584
		B_2O_3	1303-86-2	1-10	2.5	0.2865
Lead Wire-Dumet (18.6 mg)	Core material (14.136 mg)	Ni	7440-02-0	41-43	42.15	5.958324
		Fe	7439-89-6	balance	57.85	8.177676
	Cladding copper (4.464 mg)	Cu	7440-50-8	100	100	4.464
Dice (0.05 mg)		Si	7440-21-3	70.9	70.9	0.03545
		Al	7429-90-5	0.1	0.1	0.00005
		Ag	7440-22-4	28.6	28.6	0.0143
		Ni	7440-02-0	0.4	0.4	0.0002
Ink (0.19 mg)		C	7440-44-0	100	100	0.19

Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

Chemical Composition of Diode (LL-41 Glass)



Weight: 129.9 mg / pc

15-Nov-07

<table>
<tr><th colspan="2">Make up of material</th><th>Chemical Composition</th><th>CAS No.</th><th>Content Spec. (%)</th><th>Content (%)</th><th>Substance Weight (mg)</th></tr>
<tr><td colspan="2" rowspan="2">Plating (0.4 mg)</td><td>Sn</td><td>7440-31-5</td><td>99.95 min.</td><td>99.97</td><td>0.39988</td></tr>
<tr><td>Others</td><td>——</td><td>0.05 max.</td><td>0.03</td><td>0.00012</td></tr>
<tr><td colspan="2" rowspan="4">Glass Sleeve (47.395 mg)</td><td>PbO</td><td>1317-36-8</td><td>50 min.</td><td>60.5</td><td>28.673975</td></tr>
<tr><td>SiO2</td><td>7631-86-9</td><td>10-50</td><td>33</td><td>15.64035</td></tr>
<tr><td>K2O</td><td>12136-45-7</td><td>1-10</td><td>4</td><td>1.8958</td></tr>
<tr><td>B2O3</td><td>1303-86-2</td><td>1-10</td><td>2.5</td><td>1.184875</td></tr>
<tr><td rowspan="3">Lead Wire-Dumet (81.64 mg)</td><td rowspan="2">Core material (62.0464 mg)</td><td>Ni</td><td>7440-02-0</td><td>41-43</td><td>42.15</td><td>26.1525576</td></tr>
<tr><td>Fe</td><td>7439-89-6</td><td>balance</td><td>57.85</td><td>35.8938424</td></tr>
<tr><td>Cladding copper (19.5936 mg)</td><td>Cu</td><td>7440-50-8</td><td>100</td><td>100</td><td>19.5936</td></tr>
<tr><td colspan="2" rowspan="4">Dice (0.165 mg)</td><td>Si</td><td>7440-21-3</td><td>70.9</td><td>70.9</td><td>0.116985</td></tr>
<tr><td>Al</td><td>7429-90-5</td><td>0.1</td><td>0.1</td><td>0.000165</td></tr>
<tr><td>Ag</td><td>7440-22-4</td><td>28.6</td><td>28.6</td><td>0.04719</td></tr>
<tr><td>Ni</td><td>7440-02-0</td><td>0.4</td><td>0.4</td><td>0.00066</td></tr>
<tr><td colspan="2">Ink (0.3 mg)</td><td>C</td><td>7440-44-0</td><td>100</td><td>100</td><td>0.3</td></tr>
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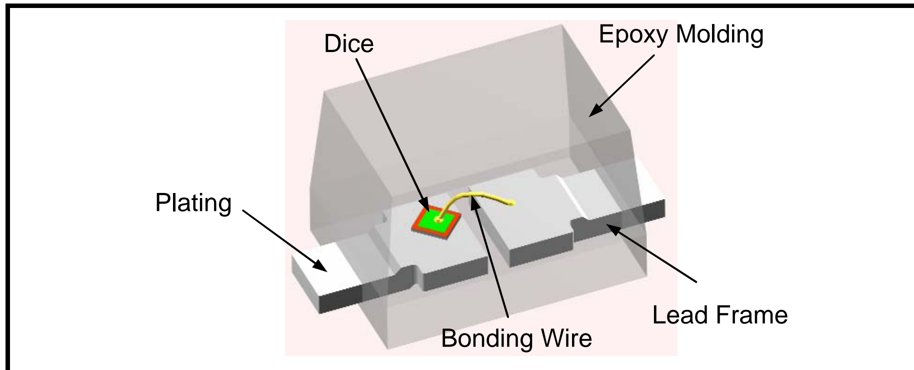
Note: Lead (Pb) in glass of electronic components is exempted from RoHS directive (EU Directive 2002/95/EC)

Chemical Composition of Diode (SOD-123)

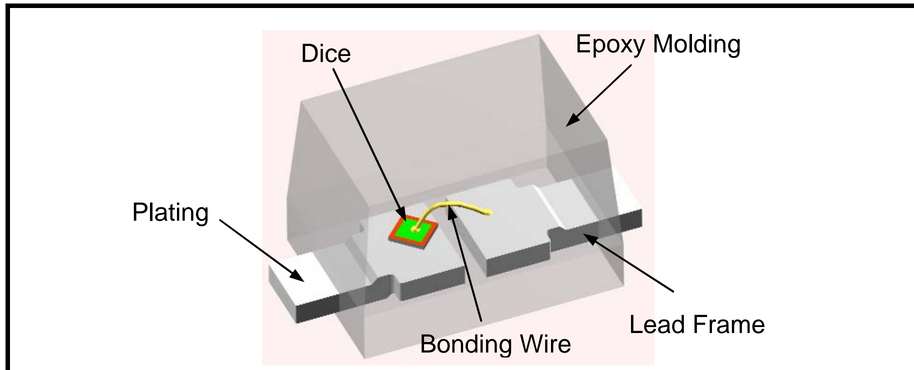


Weight: 9.15 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.051 mg)		Sn	7440-31-5	99.95 min.	99.97	0.0509847
		Others	——	0.05 max.	0.03	0.0000153
Epoxy Molding (6.627 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	5.182314
		Cristobalite	14464-46-1	0 - 1	0.5	0.033135
		Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.6627
		Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.629565
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.099405
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.019881
Bonding Wire (0.005 mg)		Au	7440-57-5	99.99 min.	99.998	0.0049999
		Others	——	0.01 max.	0.002	0.0000001
Lead Frame (2.417 mg)		Ni	7440-02-0	40 - 42	40.34	0.9750178
		Fe	7439-89-6	balance	59.66	1.4419822
Dice (0.05 mg)	Basis	Si	7440-21-3	72.5	72.5	0.03625
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.00045
	Back Metal	Au	7440-57-5	26.6	26.6	0.0133

Chemical Composition of Diode (SOD-323)

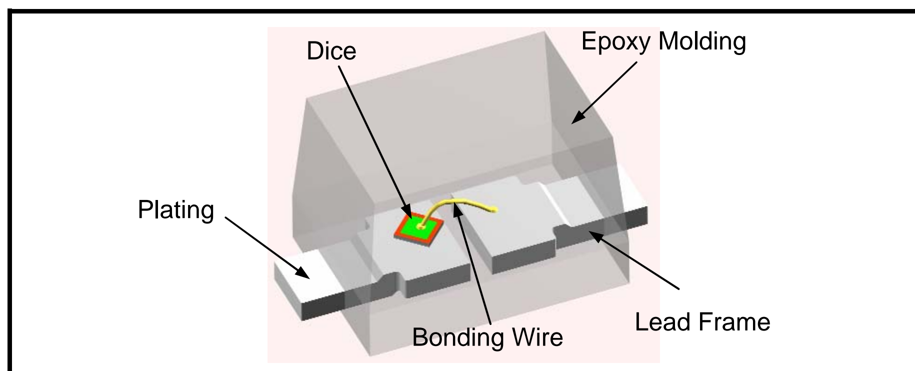


Weight: 4.6 mg / pc

15-Nov-07

Make up of material		**Chemical Composition**	**CAS No.**	**Content Spec. (%)**	**Content (%)**	**Substance Weight (mg)**
Plating (0.034 mg)		Sn	7440-31-5	99.95 min.	99.97	0.0339898
		Others	——	0.05 max.	0.03	0.0000102
Epoxy Molding (3.4065 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	2.663883
		Cristobalite	14464-46-1	0 - 1	0.5	0.0170325
		Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.34065
		Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.3236175
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.0510975
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0102195
Bonding Wire (0.0045 mg)		Au	7440-57-5	99.99 min.	99.998	0.00449991
		Others	——	0.01 max.	0.002	0.00000009
Lead Frame (1.105 mg)		Ni	7440-02-0	40 - 42	40.34	0.445757
		Fe	7439-89-6	balance	59.66	0.659243
Dice (0.05 mg)	Basis	Si	7440-21-3	72.5	72.5	0.03625
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.00045
	Back Metal	Au	7440-57-5	26.6	26.6	0.0133

Chemical Composition of Diode (SOD-523)

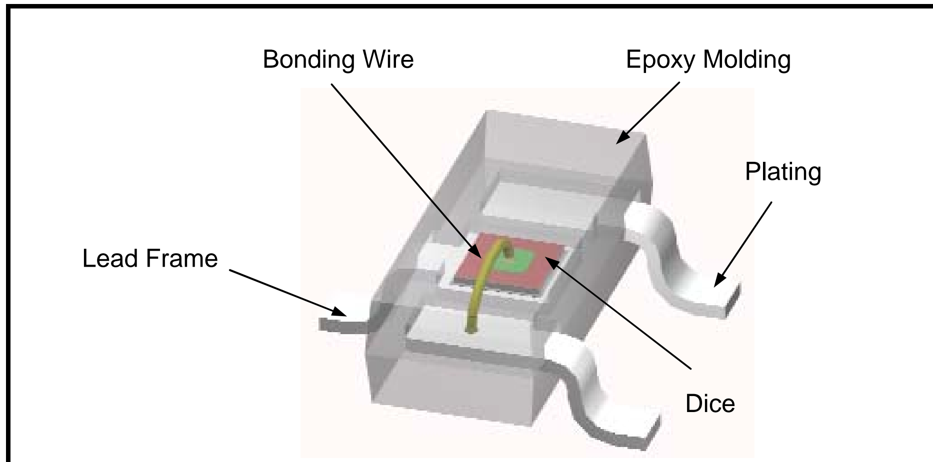


Weight: 1.47 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.018 mg)		Sn	7440-31-5	99.95 min.	99.97	0.0179946
		Others	——	0.05 max.	0.03	0.0000054
Epoxy Molding (0.8475 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	0.662745
		Cristobalite	14464-46-1	0 - 1	0.5	0.0042375
		Bisphenol-A Epoxy Resin	1675-54-3	3- 20	10	0.08475
		Phenolic Resin Water-Soluble	9003-35-4	2- 15	9.5	0.0805125
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.0127125
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0025425
Bonding Wire (0.0035 mg)		Au	7440-57-5	99.99 min.	99.998	0.00349993
		Others	——	0.01 max.	0.002	0.00000007
Lead Frame (0.553 mg)		Ni	7440-02-0	40 - 42	40.34	0.2230802
		Fe	7439-89-6	balance	59.66	0.3299198
Dice (0.048 mg)	Basis	Si	7440-21-3	72.5	72.5	0.0348
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.000432
	Back Metal	Au	7440-57-5	26.6	26.6	0.012768

Chemical Composition of Diode (SOT-23 Single Diode)

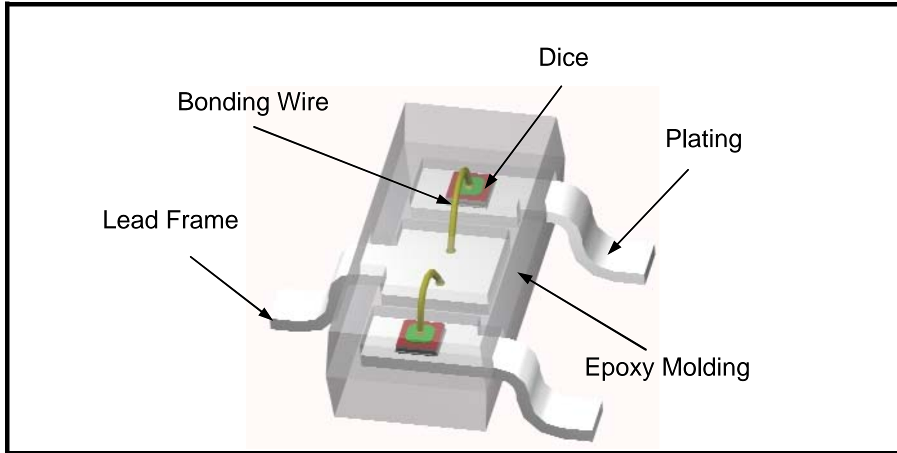


Weight: 8.72 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.14 mg)		Sn	7440-31-5	99.95 min.	99.97	0.139958
		Others	——	0.05 max.	0.03	0.000042
Epoxy Molding (6.0033 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	4.6945806
		Cristobalite	14464-46-1	0 - 1	0.5	0.0300165
		Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.60033
		Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.5703135
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.0900495
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0180099
Bonding Wire (0.038 mg)		Au	7440-57-5	99.99 min.	99.998	0.03799924
		Others	——	0.01 max.	0.002	0.00000076
Lead Frame (2.526 mg)		Ni	7440-02-0	40 - 42	40.34	1.0189884
		Fe	7439-89-6	balance	59.66	1.5070116
Dice (0.0127 mg)	Basis	Si	7440-21-3	72.5	72.5	0.0092075
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.0001143
	Back Metal	Au	7440-57-5	26.6	26.6	0.0033782

Chemical Composition of Diode (SOT-23 Double Diode)

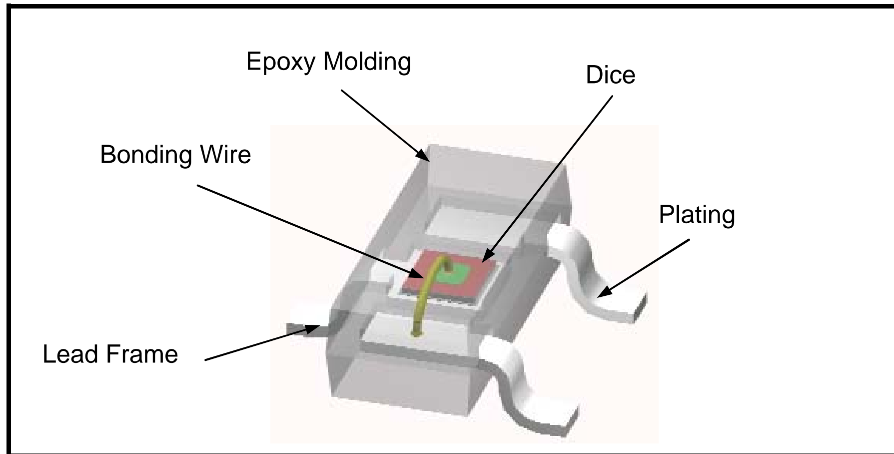


Weight: 8.72 mg / pc

15-Nov-07

<table>
<tr><th colspan="2">Make up of material</th><th>Chemical Composition</th><th>CAS No.</th><th>Content Spec. (%)</th><th>Content (%)</th><th>Substance Weight (mg)</th></tr>
<tr><td colspan="2" rowspan="2">Plating (0.14 mg)</td><td>Sn</td><td>7440-31-5</td><td>99.95 min.</td><td>99.97</td><td>0.139958</td></tr>
<tr><td>Others</td><td>——</td><td>0.05 max.</td><td>0.03</td><td>0.000042</td></tr>
<tr><td colspan="2" rowspan="6">Epoxy Molding (5.9526 mg)</td><td>Crystalline Silica (Quartz)</td><td>14808-60-7</td><td>70 - 90</td><td>78.2</td><td>4.6549332</td></tr>
<tr><td>Cristobalite</td><td>14464-46-1</td><td>0 - 1</td><td>0.5</td><td>0.029763</td></tr>
<tr><td>Bisphenol-A Epoxy Resin</td><td>1675-54-3</td><td>3 - 20</td><td>10</td><td>0.59526</td></tr>
<tr><td>Phenolic Resin Water-Soluble</td><td>9003-35-4</td><td>2 - 15</td><td>9.5</td><td>0.565497</td></tr>
<tr><td>Antimony Trioxide</td><td>1309-64-4</td><td>0.1 - 3</td><td>1.5</td><td>0.089289</td></tr>
<tr><td>Carbon Black</td><td>1333-86-4</td><td>0.1 - 0.5</td><td>0.3</td><td>0.0178578</td></tr>
<tr><td colspan="2" rowspan="2">Bonding Wire (0.076 mg)</td><td>Au</td><td>7440-57-5</td><td>99.99 min.</td><td>99.998</td><td>0.07599848</td></tr>
<tr><td>Others</td><td>——</td><td>0.01 max.</td><td>0.002</td><td>0.00000152</td></tr>
<tr><td colspan="2" rowspan="2">Lead Frame (2.526 mg)</td><td>Ni</td><td>7440-02-0</td><td>40 - 42</td><td>40.34</td><td>1.0189884</td></tr>
<tr><td>Fe</td><td>7439-89-6</td><td>balance</td><td>59.66</td><td>1.5070116</td></tr>
<tr><td rowspan="3">Dice (0.0254 mg)</td><td>Basis</td><td>Si</td><td>7440-21-3</td><td>72.5</td><td>72.5</td><td>0.018415</td></tr>
<tr><td>Obverse Metal</td><td>Al</td><td>7429-90-5</td><td>0.9</td><td>0.9</td><td>0.0002286</td></tr>
<tr><td>Back Metal</td><td>Au</td><td>7440-57-5</td><td>26.6</td><td>26.6</td><td>0.0067564</td></tr>
</table>

Chemical Composition of Diode (SOT-323 Single Diode)



Weight: 5 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.08 mg)		Sn	7440-31-5	99.95 min.	99.97	0.079976
		Others	——	0.05 max.	0.03	0.000024
Epoxy Molding (3.4373 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	2.6879686
		Cristobalite	14464-46-1	0 - 1	0.5	0.0171865
		Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.34373
		Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.3265435
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.0515595
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0103119
Bonding Wire (0.022 mg)		Au	7440-57-5	99.99 min.	99.998	0.02199956
		Others	——	0.01 max.	0.002	0.00000044
Lead Frame (1.448 mg)		Ni	7440-02-0	40 - 42	40.34	0.5841232
		Fe	7439-89-6	balance	59.66	0.8638768
Dice (0.0127 mg)	Basis	Si	7440-21-3	72.5	72.5	0.0092075
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.0001143
	Back Metal	Au	7440-57-5	26.6	26.6	0.0033782

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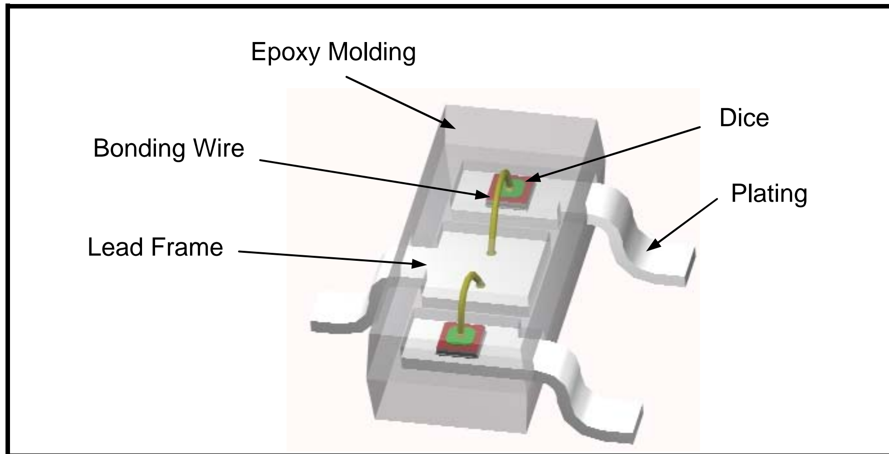
Chemical Composition of Diode (SOT-323 Double Diode)



Weight: 5 mg / pc

15-Nov-07

Make up of material		Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.08 mg)		Sn	7440-31-5	99.95 min.	99.97	0.079976
		Others	——	0.05 max.	0.03	0.000024
Epoxy Molding (3.4026 mg)		Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	2.6608332
		Cristobalite	14464-46-1	0 - 1	0.5	0.017013
		Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.34026
		Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.323247
		Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.051039
		Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0102078
Bonding Wire (0.044 mg)		Au	7440-57-5	99.99 min.	99.998	0.04399912
		Others	——	0.01 max.	0.002	0.00000088
Lead Frame (1.448 mg)		Ni	7440-02-0	40 - 42	40.34	0.5841232
		Fe	7439-89-6	balance	59.66	0.8638768
Dice (0.0254 mg)	Basis	Si	7440-21-3	72.5	72.5	0.018415
	Obverse Metal	Al	7429-90-5	0.9	0.9	0.0002286
	Back Metal	Au	7440-57-5	26.6	26.6	0.0067564